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VERSION WITH MARKED-UP CHANGES

Additions/Deletions to the Abstract:

A semiconductor package includes a semiconductor chip which is mounted on a die pad which is smaller than the semiconductor chip, a die pad supporter which supports the die pad, the die pad supporter having a stress absorbing portion, [and] the stress absorbing portion [which] is disposed under the semiconductor chip.

Additions/Deletions to the Specification:

Page 3, lines 19-23:

As shown in Fig. 1, a die pad 2 is formed at a central portion of a leadframe 1. Four die pad supporters 3 support the die pad 2. The die pad supporters 3 are located at right angles from each other. A size of the die pad 2 is smaller than the size of a semiconductor chip 11. That is, a configuration of the die pad 2 is [larger] smaller than that of the semiconductor chip.

Page 4, line 26 through to page 5, line 2:

After the semiconductor chip 11 is fixed on the die pad 2[. Electrode],electrode pads 15 arranged on a surface of the semiconductor chip 11 are connected to the inner leads through wires 13. During a wire-bonding step, the leadframe 1 is clamped on the heat stage 70 by a clasper 71, as shown in Fig. 8. A rear surface of the semiconductor chip 11 is vacuumed by a vacuuming portion 73 for holding the semiconductor chip 11

on the heat stage, as also shown in Fig. 8.

Page 6, lines 7-11:

Also, a configuration of the stress-absorbing portions 7 can be [used a] S-shaped stress-absorbing portions 30 [20], as shown in Fig. 3. In this case, as a protruding portion [21] 31 is symmetrical with a concave portion 32 [22], a changing in [a] lateral or [a] vertical directions of the die pad supporters 3 causing the expansion of die pad supporter 3 can be reduced.

Additions/Deletions to the Claims:

1. (Amended) A semiconductor device comprising:

a die pad;

a die pad supporter which supports said die pad;

a plurality of inner leads arranged to surround said die pad; and

a semiconductor chip which has a size larger in area than that of said die pad and which is mounted on said die pad;

wherein said die pad supporter has a stress absorbing portion which is located between said die pad and ends of said inner leads, [and]

wherein said semiconductor chip is disposed over the stress absorbing portion, and

wherein a part of said die pad supporter is located between a pair of said inner leads and extends along the pair of said inner leads.

5. (Amended) A semiconductor device comprising:

a die pad;

a die pad supporter which supports the die pad;

a plurality of inner [lead] leads arranged to surround the die pad; and

a semiconductor chip which has a size larger in area than that of said die pad
and which is mounted on said die pad;

wherein said die pad supporter has a first portion, a pair of second portions, and
a pair of third portions, wherein said first portion is disposed between a pair of said
inner leads and [disposed substantially parallel with] extends along the pair of said inner
leads, and wherein one end of each of said second portions connect to one end of said
first portion, and said each of said second [portion] portions extend [to different] in a
direction different from a direction [of] in which said first portion is extended, and
wherein one end of each of said third portions each [connect the other] connects to
another end of respective said second portions and another [the other] end of each of
said third portions are connected to the die pad.

6. (Amended) A semiconductor device comprising:

a die pad[:];

a die pad supporter which supports the die pad;

a plurality of inner leads arranged to surround the die pad; and

a semiconductor chip which has a size larger in area than that of said die pad
and which is mounted on said die pad;

wherein said die pad supporter includes a frame portion which has a rectangular shape, a first portion connected between a side portion of said frame portion [to] and the die pad, and a second [portions] portion which extends from a corner portion of said frame portion to between a pair of said inner leads, and wherein the frame portion and the first portion are disposed between the inner leads and the die pad.

7. (Amended) A semiconductor device according to claim 6, comprising a plurality of said second portions, wherein each of said second portions is disposed between said inner leads and disposed substantially parallel with said inner leads adjacent to the second portions.

9. (Amended) A semiconductor device according to claim 6, wherein said semiconductor chip has a first surface on which [is] an integrated circuit is formed and a second surface which is opposite [side of] said first surface, and wherein said frame portion is arranged [over] adjacent the second surface of the semiconductor chip.

10. (Amended) A semiconductor device comprising:
a die pad;
a plurality of inner leads arranged to surround the die pad;
a semiconductor chip which has a size larger in area than that of said die pad
and which is mounted on said die pad;
a frame portion which substantially surrounds the die pad and is disposed

between said inner leads and said die pad;

first die pad supporters each of which supports the frame portion from four directions; and

a second die pad supporter which connects the frame portion and said die pad;

wherein said second die pad supporter is extended [to] along a direction different [direction] from directions [of] in which the first die pad supporters [is] are extended.

11. (Amended) A semiconductor device according to claim 10, wherein said semiconductor chip [disposes] is disposed on the frame portion.

12. (Amended) A semiconductor device according to claim 11, wherein said first die pad supporters [supporter] and said second die pad supporter are staggered at the frame portion.

13. (Amended) A semiconductor device according to claim 10, wherein said frame portion has substantially rectangular shape, and wherein said first die pad supporters [supporter] each support substantially corner portions of said frame portion, and wherein said second die pad supporter connects at a side portion of said frame portion.